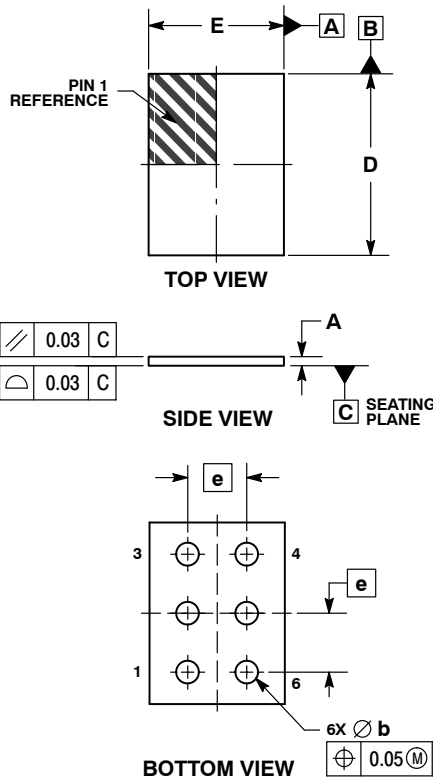




SCALE 4:1

**WLCSP6 2.00x1.49x0.10**  
CASE 567UF  
ISSUE O

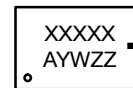
DATE 21 APR 2017



## NOTES:

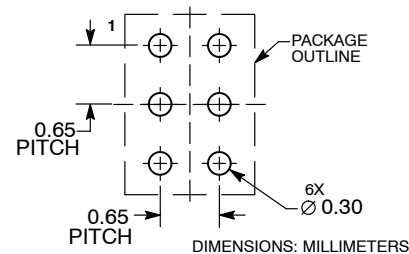
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.08	0.10	0.12
b	0.27	0.30	0.33
D	1.95	2.00	2.05
E	1.44	1.49	1.54
e	0.65 BSC		

**GENERIC MARKING DIAGRAM\***


XXX = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
ZZ = Assembly Lot  
■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

**RECOMMENDED SOLDERING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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